



SUNPLUS

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凌陽科技股份有限公司 2024 Q2 財務報告

莊濟安

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Make difference

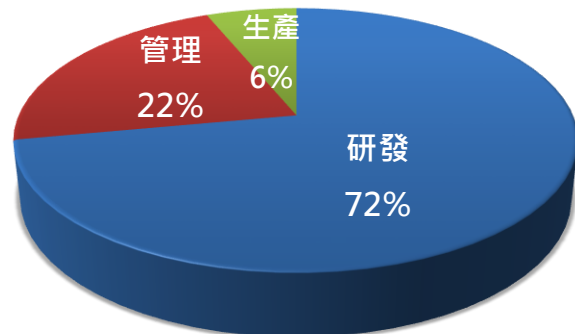
集團企業

	專業	持股比	股票代號
	凌陽科技股份有限公司 (592m shares) 數位影音娛樂多媒體系統單晶片設計與矽智財設計	100%	TWSE#2401
	凌通科技股份有限公司 (109m shares) 語音、LCD、數位影像處理與MCU晶片設計	48%	TWSE#4952
	凌陽創新科技股份有限公司 (58m shares) 網路攝影機、影像信號處理控制與人機介面控制晶片設計	57%	TWSE#5236
	景相科技股份有限公司 (24m shares) 車用微控制器與USB儲存ASIC	100%	

* Based on 2024/6/30 Consolidated-holding by Sunplus

人力結構

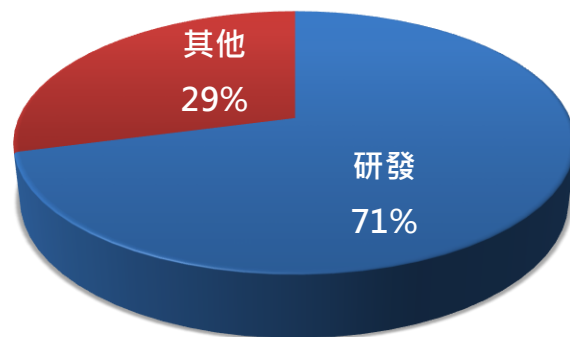
集團人力



集團員工人數 / 研發人員
1,053 / 760

42%碩士以上

凌陽科技人力



凌陽科技員工人數 / 研發人員
327 / 232

63%碩士以上

* Data by 2024/6/30

上半年 合併綜合損益表

(新台幣佰萬元)	2024 1H		2023 1H		年同比	備註
營業收入淨額	3,134	100%	2,612	100%	20%	S+45%、G+23%、IT+6%
營業成本	1,606	51%	1,378	53%	17%	
營業毛利	1,528	49%	1,234	47%	24%	庫存去化、減少提列存貨跌價損失
研究發展費用	995	32%	1,016	39%	(2%)	
銷售管理費用	450	14%	348	13%	30%	權利金增加
營業淨利	82	3%	(130)	(5%)	(163%)	
營業外收入及支出	393	13%	118	5%	232%	2024處分芯鼎持股
本期淨利	425	14%	(51)	(2%)	(937%)	
其他綜合損益	36	1%	(3)	(0%)	(1349%)	
本期綜合損益總額	460	15%	(54)	(2%)	(959%)	
淨利歸屬於：						
本公司業主	234	7%	(175)	(7%)	(234%)	
非控制權益	190	6%	124	5%	53%	
每股盈餘 (元)	0.40		(0.30)			

第二季 合併綜合損益表

(新台幣佰萬元)	2024 2Q		2024 1Q		2023 2Q		季同比	年同比	備註
營業收入淨額	1,788	100%	1,347	100%	1,418	100%	33%	26%	QoQ : S+48%、G+46%、IT+12% YoY : S+87%、G+26%、IT+1%
營業成本	919	51%	687	51%	750	53%	34%	23%	
營業毛利	869	49%	659	49%	669	47%	32%	30%	
研究發展費用	509	28%	487	36%	535	38%	4%	(5%)	光罩費用
銷售管理費用	282	16%	168	12%	175	12%	68%	61%	權利金增加
營業淨利	78	4%	4	0%	(42)	(3%)	1755%	(287%)	
營業外收入及支出	37	2%	356	26%	65	5%	(90%)	(43%)	
本期淨利	112	6%	313	23%	(2)	(0%)	(64%)	(6164%)	
其他綜合損益	55	3%	(19)	(1%)	(65)	(5%)	(385%)	(184%)	
本期綜合損益總額	167	9%	293	22%	(67)	(5%)	(43%)	(348%)	
淨利歸屬於：									
本公司業主	3	0%	232	17%	(83)	(6%)	(99%)	(103%)	
非控制權益	110	6%	81	6%	81	6%	36%	35%	
每股盈餘 (元)	0.01		0.39		(0.14)				

** EPS based on outstanding 591,994,919 shares on 2024/6/30

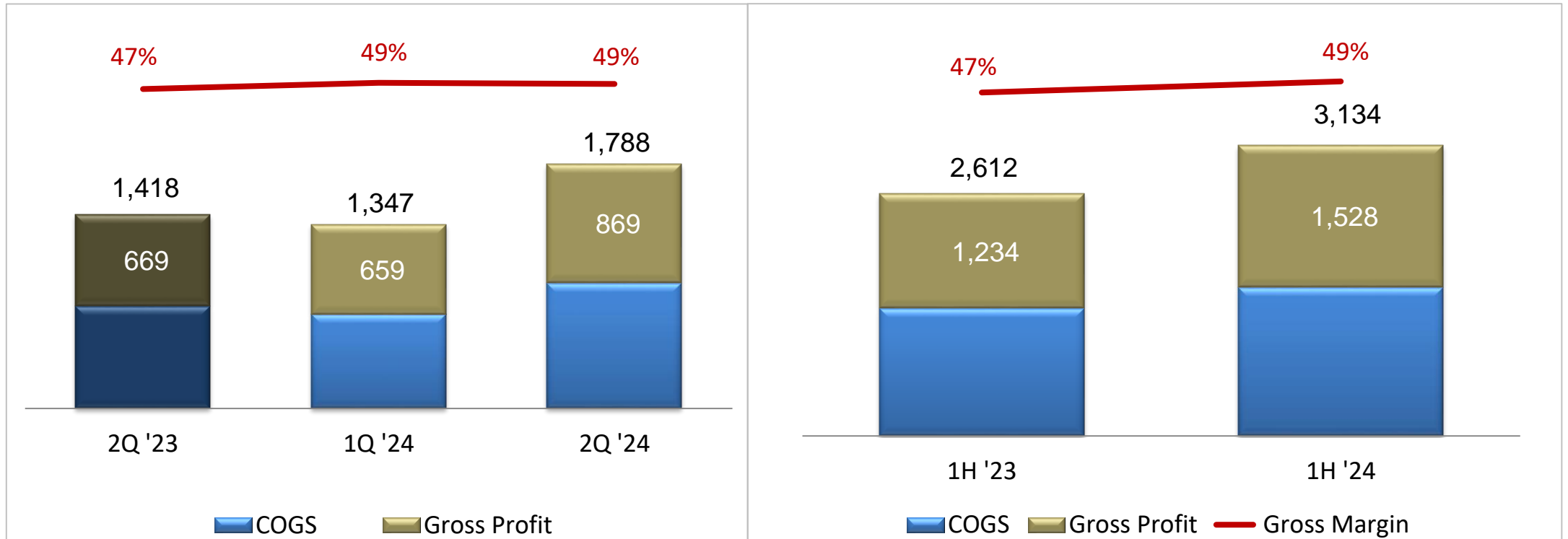
合併營收與毛利

NT\$ million

← 毛利年同比: +30% →

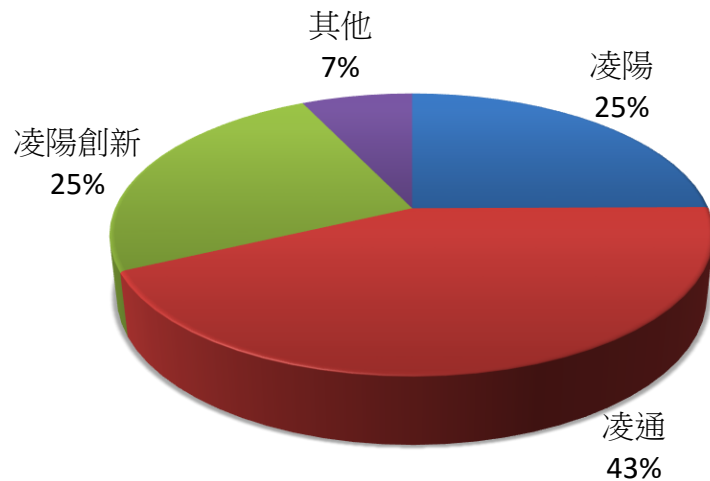
← 毛利年同比: +24% →

← 毛利季同比: +32% →

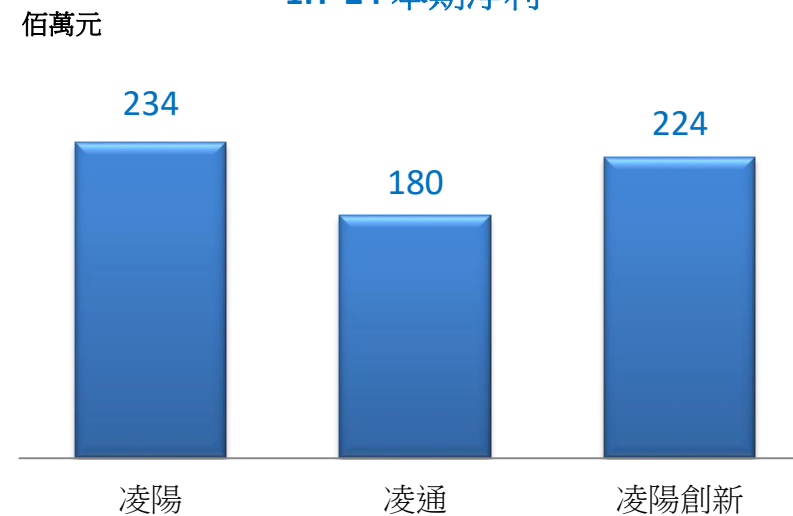


子公司貢獻

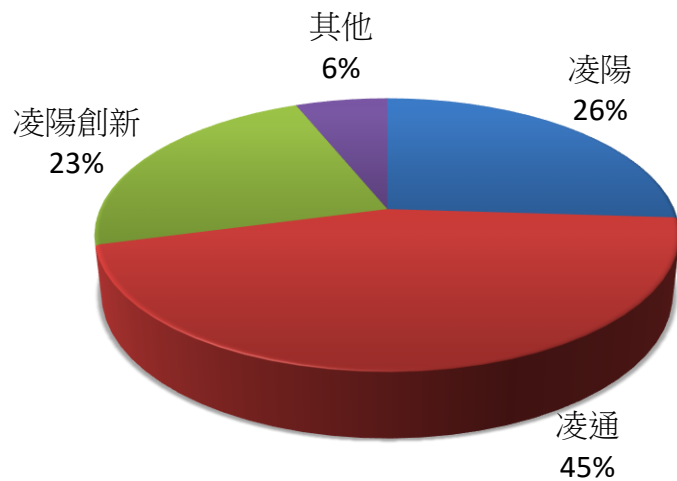
1H '24 營收淨額：3,134 MNT\$



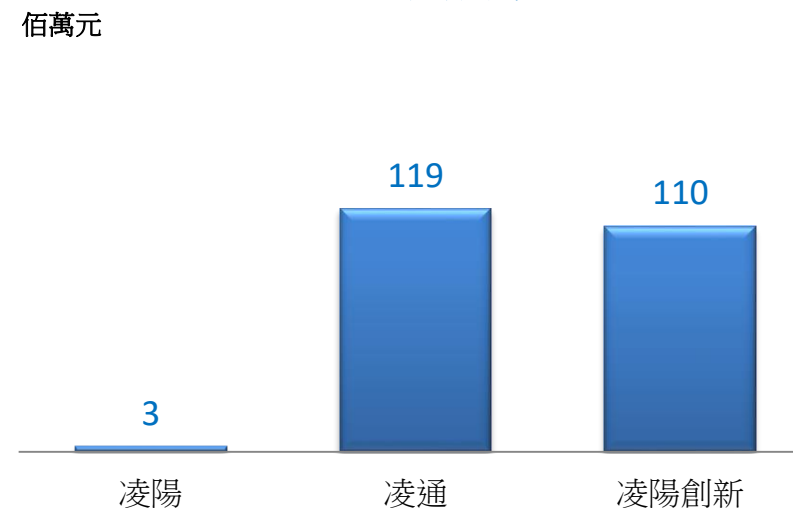
1H '24 本期淨利



2Q '24 營收淨額：1,788 MNT\$



2Q '24 本期淨利



合併資產負債表

(新台幣佰萬元)	2024 2Q	2024 1Q	2023 2Q	季同比	年同比	備註
資產總計	14,776	14,185	14,943	4%	(1%)	
現金及約當現金	4,753	4,423	3,895	7%	22%	獲利增加
透過損益按公允價值衡量之金融資產-流動	1,326	1,262	1,763	5%	(25%)	
存貨淨額	1,214	1,258	1,774	(4%)	(32%)	IT備貨
採用權益法之投資	779	791	937	(1%)	(17%)	YoY：芯鼎持股減少
透過損益按公允價值衡量之金融資產-非流動	1,638	1,656	1,516	(1%)	8%	
負債合計	3,783	3,318	4,052	14%	(7%)	
短期借款	197	162	274	22%	(28%)	
應付票據及帳款	596	364	275	64%	117%	備貨增加
其他流動負債	1,119	816	1,623	37%	(31%)	2Q：發放股利 YoY：股利金額下降
權益合計	8,725	8,644	8,738	1%	(0%)	
股東權益報酬率 %	3.86%	2.88%	(0.47%)			
每股淨值 (元)	14.83	14.69	14.85			

營業外收入及支出

(新台幣佰萬元)	<u>2024 1H</u>	<u>2023 1H</u>	<u>年同比</u>	<u>備註</u>
其他收入	50	32	58%	
外幣兌換淨利益(損失)	46	8	448%	
透過損益按公允價值衡 量之金融資產利益	(10)	99	(110%)	持有股權價值波動
採用權益法認列之關聯 企業損益份額	(21)	(32)	(35%)	權益法公司的損益
處分權益法之投資利益	310	0		2024處分芯鼎持股
<u>營業外收入及支出合計</u>	<u>393</u>	<u>118</u>	<u>232%</u>	

(新台幣佰萬元)	<u>2024 2Q</u>	<u>2024 1Q</u>	<u>2023 2Q</u>	<u>季同比</u>	<u>年同比</u>	<u>備註</u>
其他收入	20	30	21	(33%)	(5%)	
外幣兌換淨利益(損失)	13	34	15	(63%)	(19%)	
透過損益按公允價值衡 量之金融資產利益	1	(11)	25	(108%)	(97%)	持有股權價值波動
採用權益法認列之關聯 企業損益份額	(16)	(5)	(6)	232%	151%	權益法公司的損益
處分權益法之投資利益	9	301	0	(97%)		處分芯鼎持股
<u>營業外收入及支出合計</u>	<u>37</u>	<u>356</u>	<u>65</u>	<u>(90%)</u>	<u>(43%)</u>	

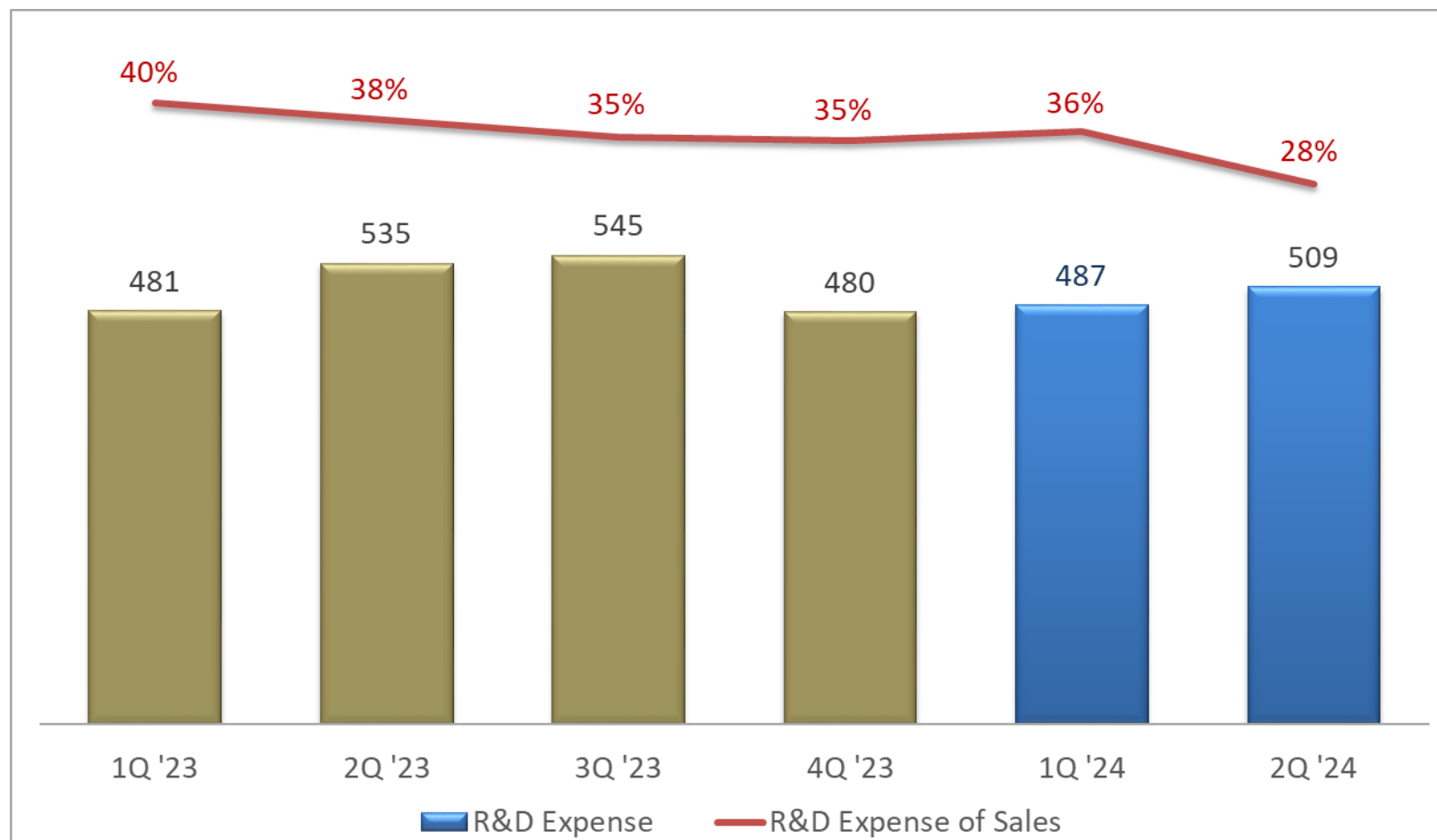
現金流量表

(新台幣佰萬元)	2024 1H	2023 1H	年同比	備註
營業活動之現金流入(出)	481	266	81%	獲利增加·去化庫存
投資活動之現金流入(出)	11	(1,156)	(101%)	2023購買貨幣型基金
融資活動之現金流入(出)	150	355	(58%)	2023銀行借款金額高
現金淨增加(減少)數	661	(533)	(224%)	
期末現金及約當現金餘額	4,753	3,895	22%	
透過損益按公允價值衡量之金融資產-流動	1,326	1,763	(25%)	
可動用金額總數	6,079	5,658	7%	獲利增加

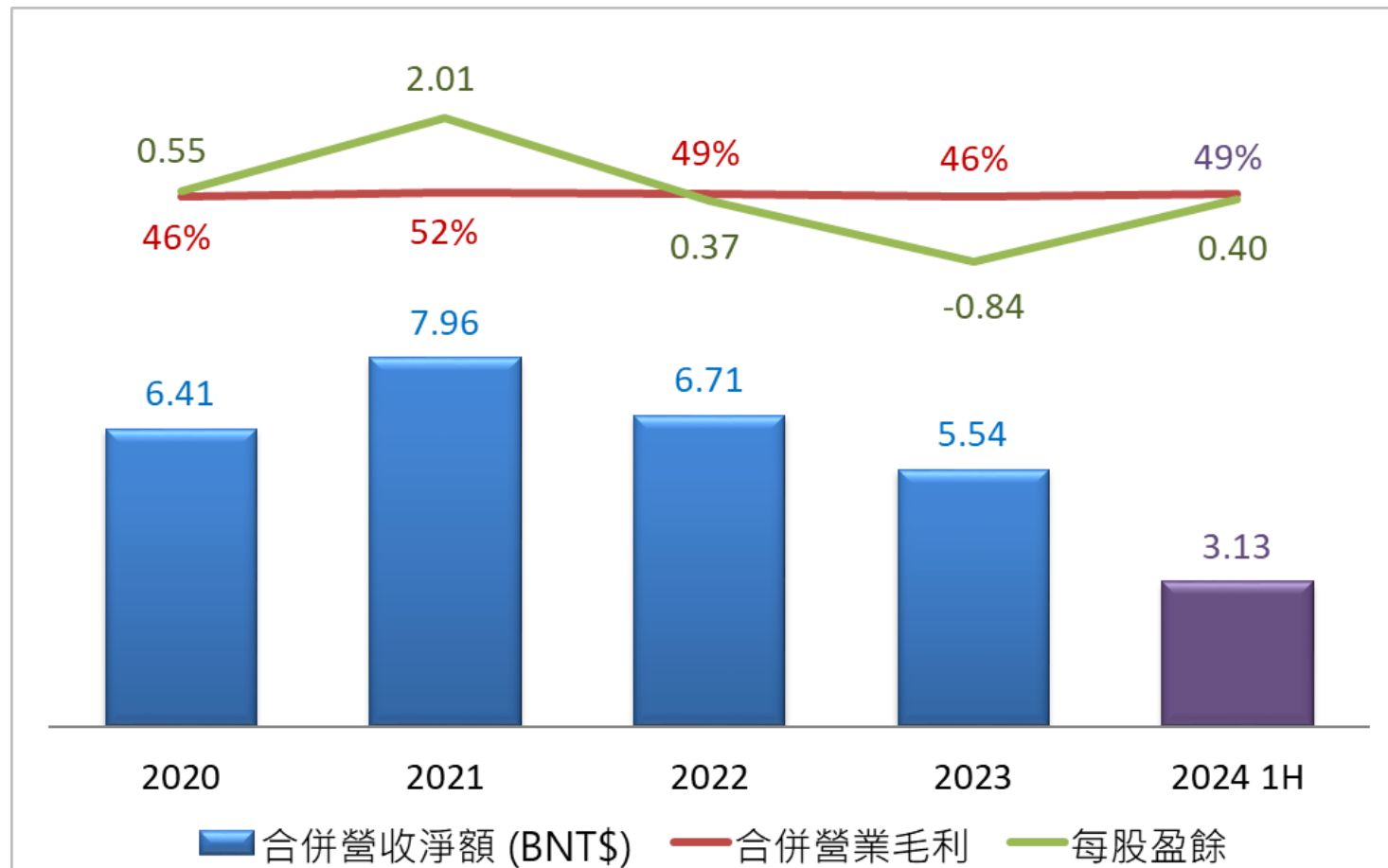
(新台幣佰萬元)	2024 2Q	2024 1Q	2023 2Q	季同比	年同比	備註
營業活動之現金流入(出)	370	111	420	232%	(12%)	Q1發年獎 YoY：備貨增加
投資活動之現金流入(出)	(64)	75	(719)	(186%)	(91%)	2023購買貨幣型基金
融資活動之現金流入(出)	18	132	75	(86%)	(76%)	2024 1Q：短借
現金淨增加(減少)數	330	331	(221)	(0%)	(249%)	
期末現金及約當現金餘額	4,753	4,423	3,895	7%	22%	
透過損益按公允價值衡量之金融資產-流動	1,326	1,262	1,763	5%	(25%)	
可動用金額總數	6,079	5,685	5,658	7%	7%	

研發費用與佔營收比 (合併)

NT\$ million



財務概況



凌陽產品組合

Automotive

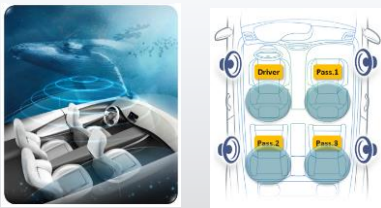
Cockpit Electronics



Automated Driving



In-cabin Acoustics



Audio

Speaker Out



Wireless Connection



Speech In



Plus 1

C1



C3



DVD



Automotive

Inside and Around the Cockpit



Cockpit Electronics

IVI
Display Audio
Cluster
HUD



Automated Driving

AVM
DMS/IMS
ADAS
E-Mirror
APA



In-cabin Acoustics

Spatial Sound
Auto-EQ
EC/NR
ITU-T Lab



Cockpit Electronics

Display Audio

Connects Vehicle to Person (Personal Device)



Apple might keep on enhancing the in-car XP



Partnering with Automakers



Focus on Deeper Integration (with Car)

Expanding App Ecosystem

Focus on Customization

iCockpit Solution

• Cluster



• In-Vehicle-Infotainment

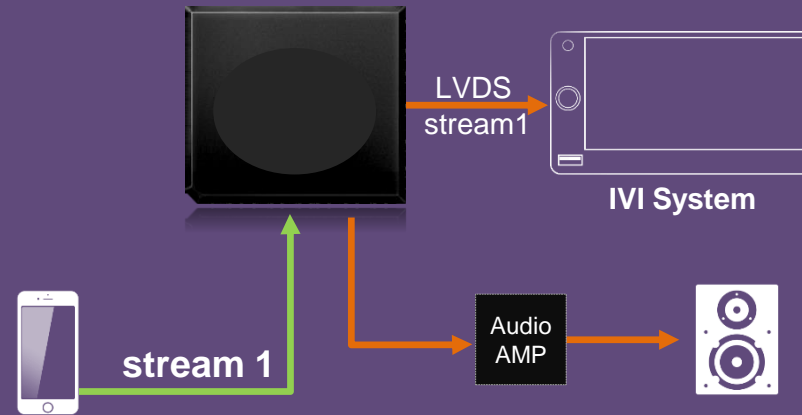


• AVM/ADAS



CarPlay Multi-Stream

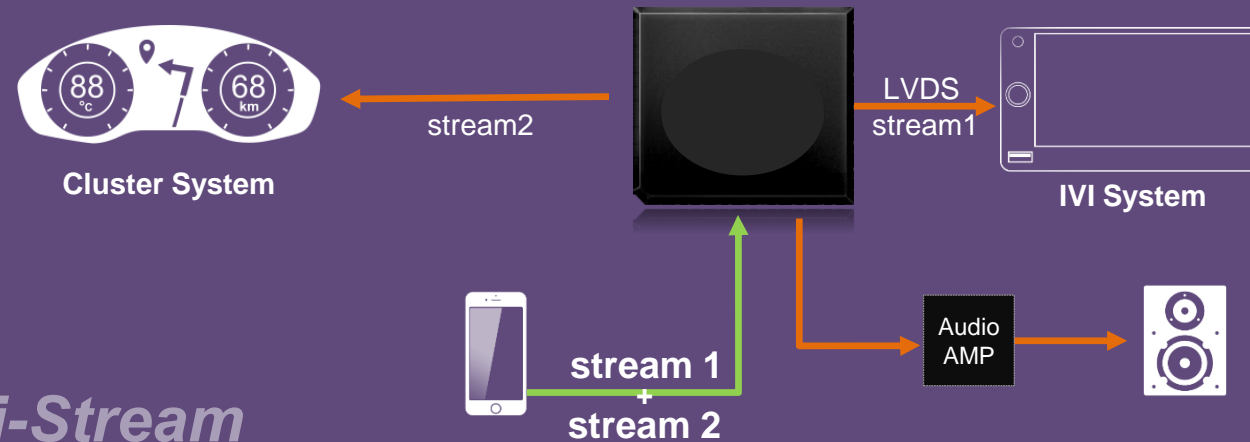
Classic CarPlay



■ Stream 1: CarPlay Functions

- Navigation, Music, Telephony, and Siri, etc.

CarPlay Multi-Stream



CarPlay Multi-Stream

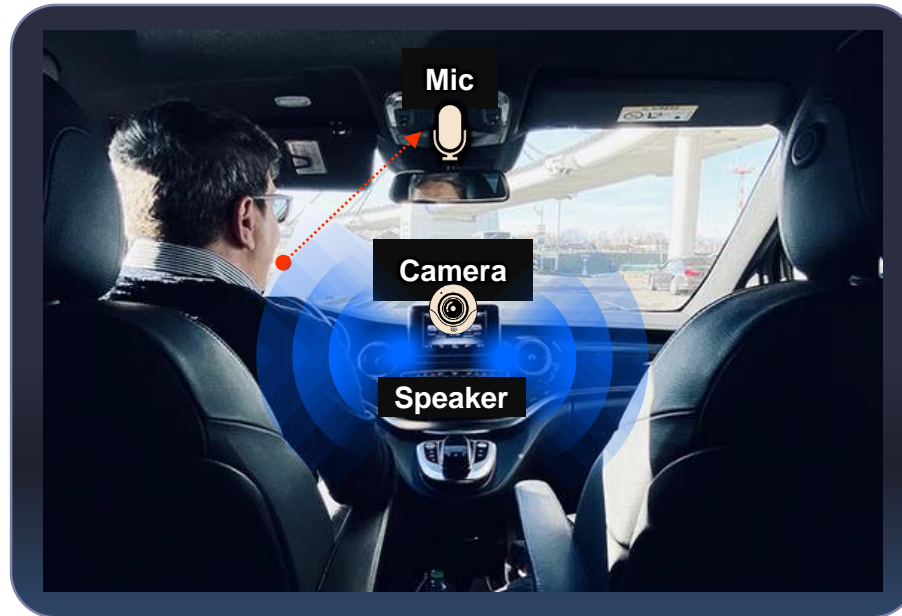
■ Stream 2: Alternative Functions

- Navigation, Sound Effect Spectrum, or Album Info
- To Cluster or HUD

iCockpit: IVI+Cluster



iCockpit : IVI+ADAS



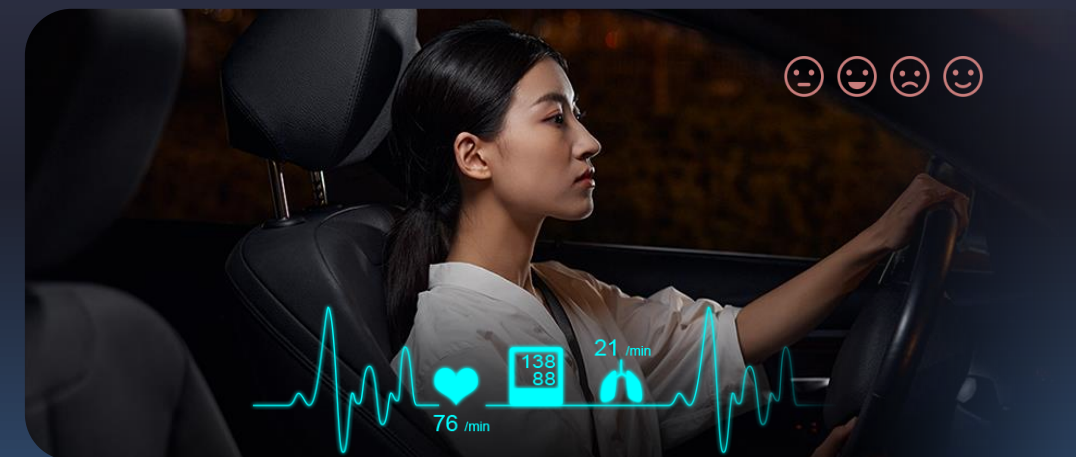
Driver ID.



Driver Monitor System (DMS)



Driver Monitoring System – Vision-based

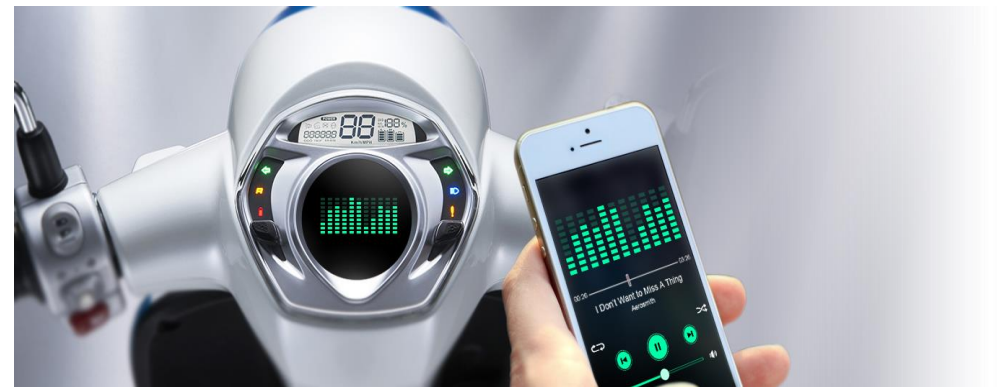


Motorcycle Cluster Market

- Scooter cluster supports smart phone link and mirroring
- Large displacement motorcycle supports CarPlay & Android Auto



Phone link
&
Mirroring



CarPlay
&
Android Auto



Motocycle Cluster solution

- 4 types reference for UI Layout (cluster, navigation, turn-by-turn, cluster + navigation)



Motocycle Cluster solution

- Wireless Connection by WiFi and Bluetooth_1 Module
- Support Helmet 1 & Helmet 2 by Bluetooth_2 Module



Automated Driving

ADAS Applications

AVM



AR HUD



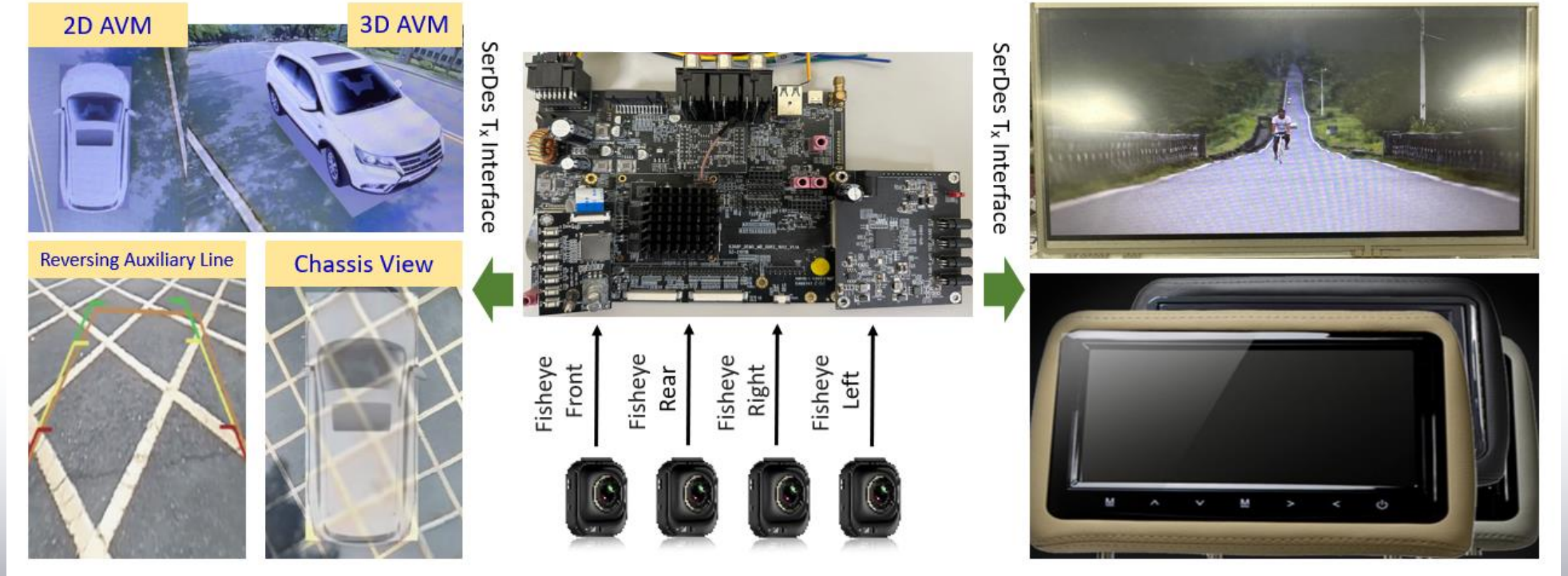
APA



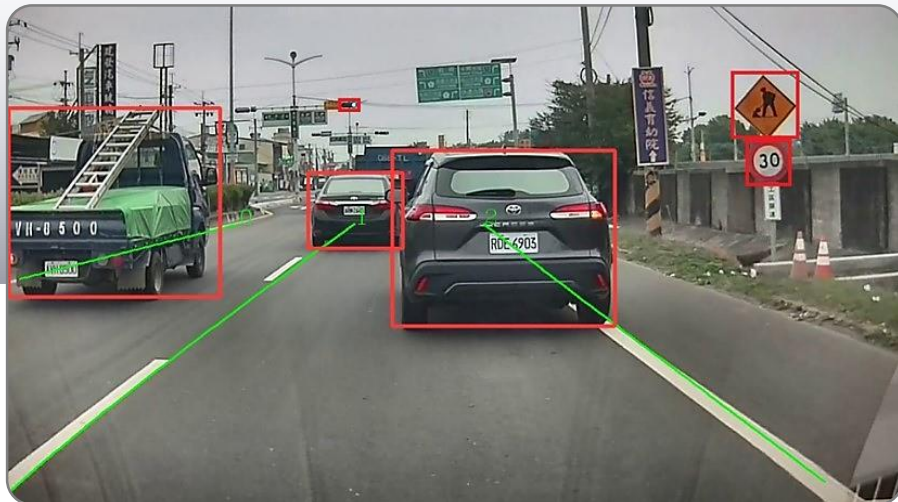
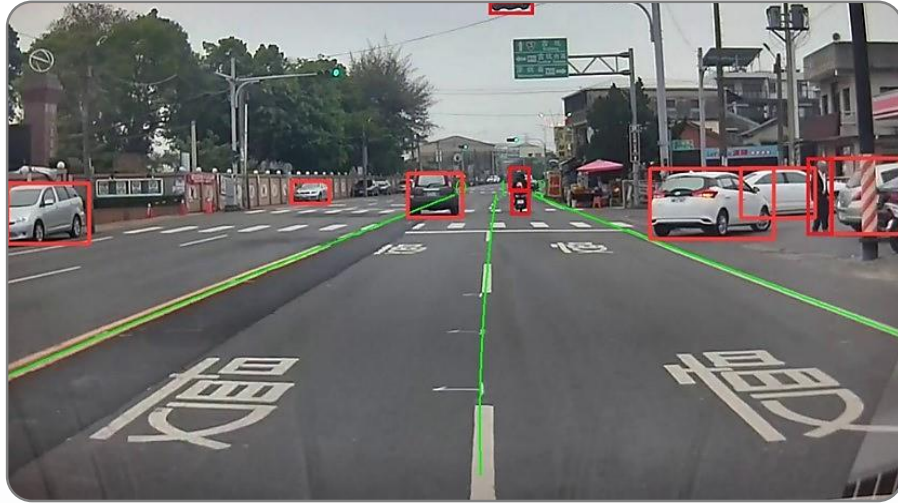
E-Mirror/CMS/DMS



AVM



Smart Vision Sensors



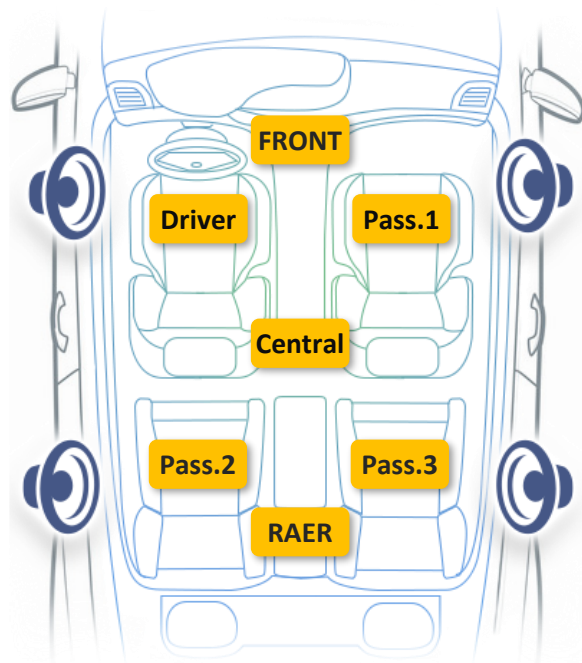
■ FHD camera inputs Detection:

- Motorcycles
- Cars
- Traffic lights
- Traffic signs
- Traffic lanes
- Pedestrians

Immersive Sound

Joy – In-cabin Acoustics

Sound Field with IMS



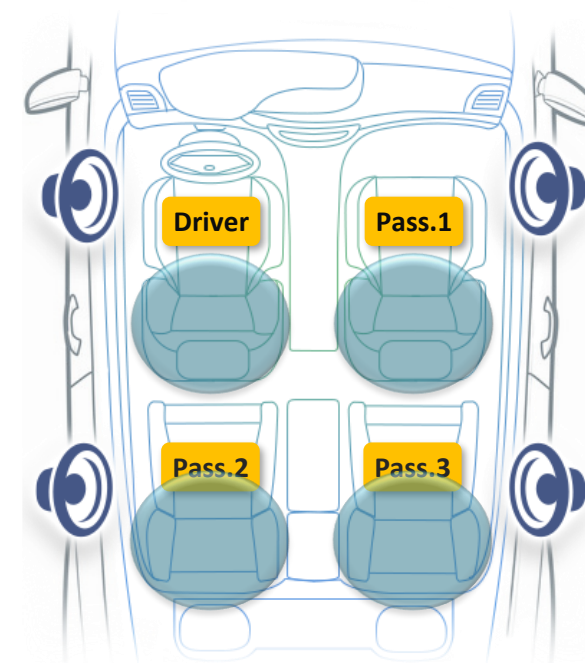
The IMS sees the occupants and feeds the info to IVI for optimal sound field settings.

Immersive Sound



Bringing the 3D surround technology, such as Dolby Atmos™, or Sunplus Spatial Sound to the cabin.

Sound Bubble (w/ ANC)

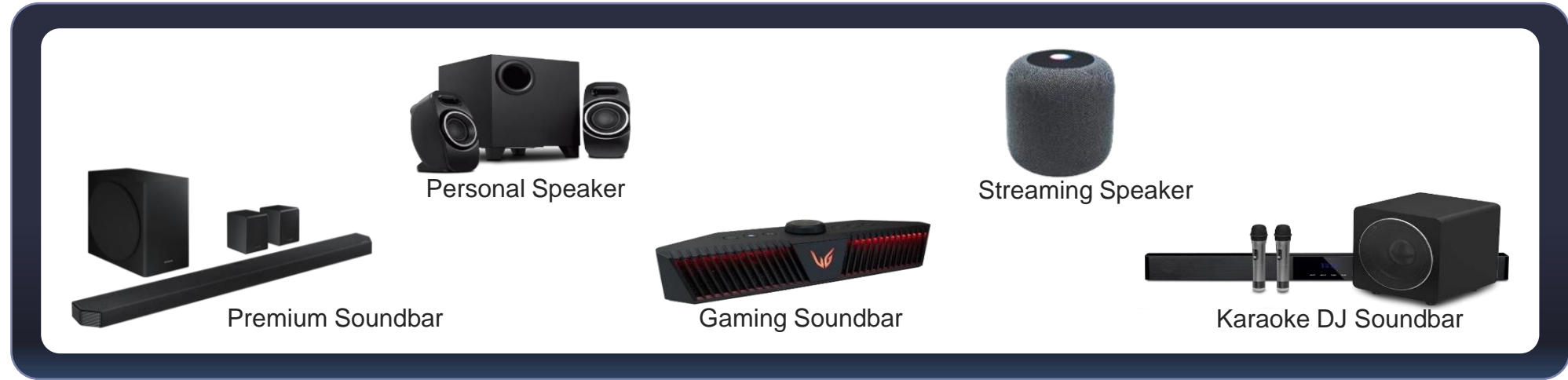


Giving every occupants a quiet zone, or independent listening zone.

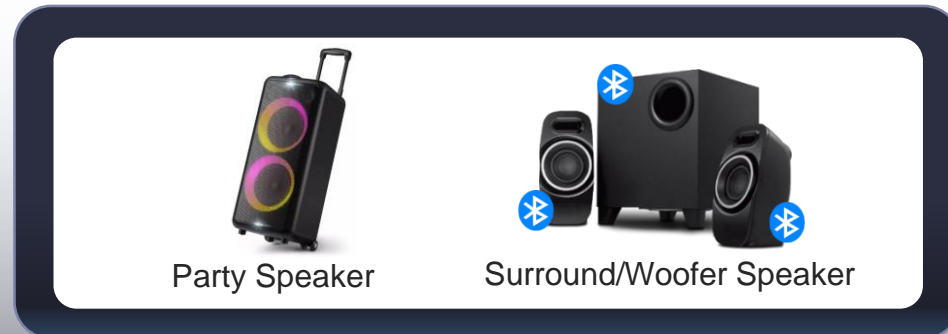
Audio

Audio Solutions

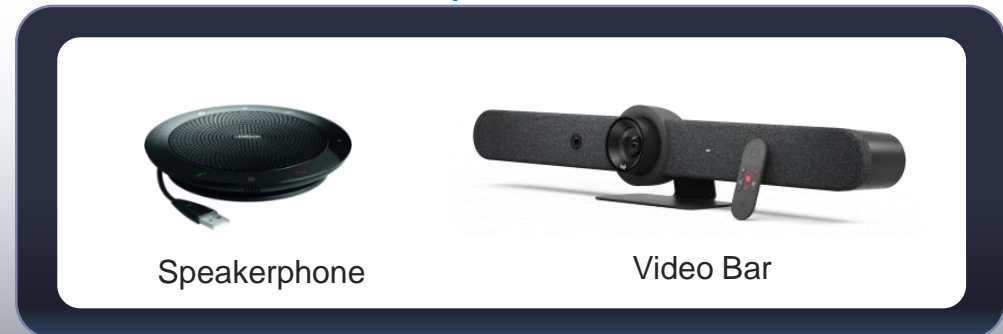
Speaker Out



Wireless Connection



Speech In



Soundbar

- Bridging the gap of Flat-panel HDTV & Home Theater



Best Cost-Performance Soundbar Solution

3D Sound Effects

- Dolby ATMOS v1.8
- DTS: X, IMAX enhanced
- MPEG-H
- Sunplus Spatial Sound

AI Sound Classifier

- Advanced AI algorithms accurately classify media content

Room Correction

- Optimize the acoustics of Main Bar, Subwoofer for room

Bluetooth v5.3

- LE Audio, LC3/LC3plus Codecs
- Multi-stream, Broadcast

Sound Tuning Tool

- Powerful GUI tuning tool supports arbitrary sound adjustment

3rd-party Algorithm

- Capable of compatible to customer legacy sound algorithm

Audio Streaming

- + External DTS Play-Fi Module
- + WiFi Module (Airplay-2, Alexa, etc.)

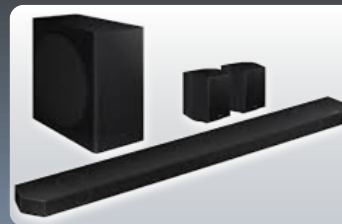


Soundbar with surround



Target Market

Innovative Bluetooth Audio ecosystem is creating



Soundbar Speaker

- Immersive 3D Surround, Wireless Sub
- AI Media Classifier, Useful Tuning Tool



Party Speaker

- Auracast for broadcast audio
- Smart DJ effects & Karaoke



Conference Speaker

- BT Dongle for transmitting audio
- AI Voice Enhanced Algorithm



Gaming Speaker

- In-house Spatial Sound Effect
- UAC, USB Audio Class to PC



Streaming Speaker

- Streaming Audio thru Mobile phone
- Diverse AP S/W ready for playback



Party Speaker



Gaming / PC Soundbar



S+ Spatial Sound 3D
Gaming/PC Soundbar

Conference Speaker

Conference Speaker

SPA101
Acoustic Echo Cancellation
Noise Reduction

Demo Video

Noise Reduction Acoustic Echo Cancellation

airlyra

Video Bar

VideoBar | SPA100P
S+ Audio Barrier
S+ AI ClearVoice

Audio Barrier

Audio Barrier

S+ AI ClearVoice

Demo Video

S+ AI ClearVoice

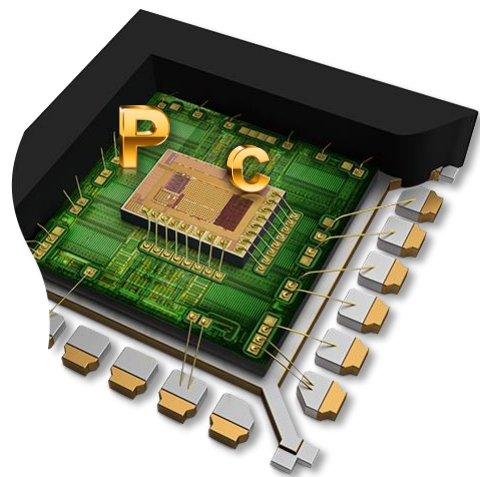
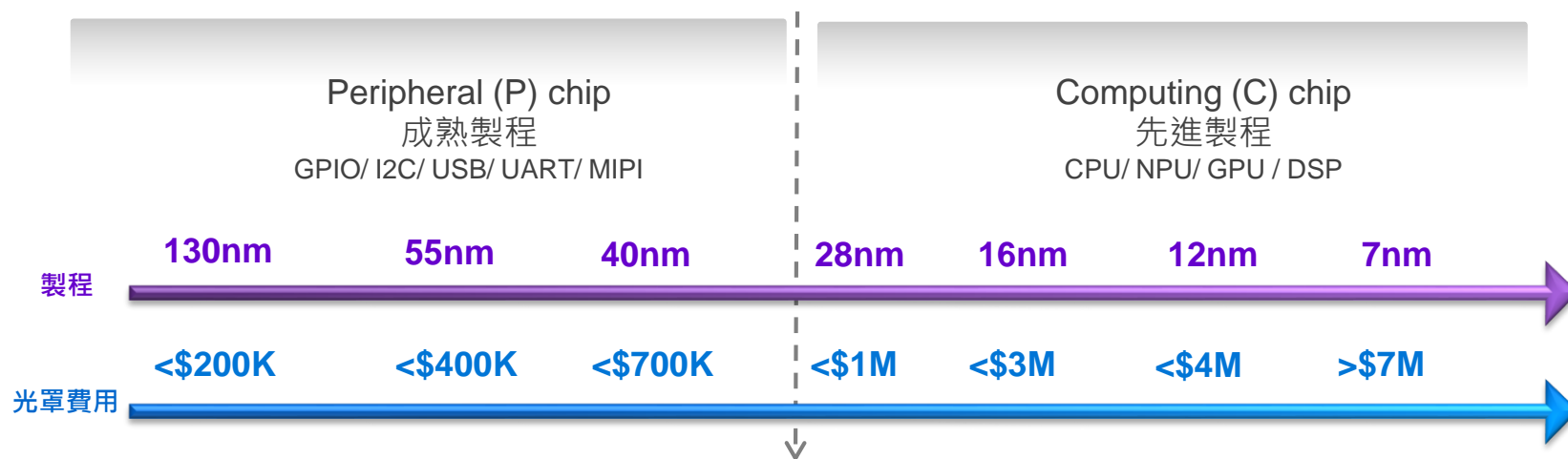
S+ Audio Barrier

airlyra

Plus 1

Plus1：共享智能運算Chiplet架構

通用高效算力結合專用周邊的 AI on Chip 解決方案



Plus1

將界面週邊P與高運算力C
區隔為兩個不同的晶粒(Chiplet)

C1 – IOT LINUX CHIP

全球市場開枝散葉



英國、挪威：
車隊物流追蹤系統



俄羅斯：
教育用機器人



荷蘭：
家用熱泵



德國：
生理辨識
工業網路協定



法國：
付費影印機
HiFi音響



比利時：
充電樁



中東：
農業管理
昆蟲辨識



印度：
工業網路閘道器

南韓：
工業控制器

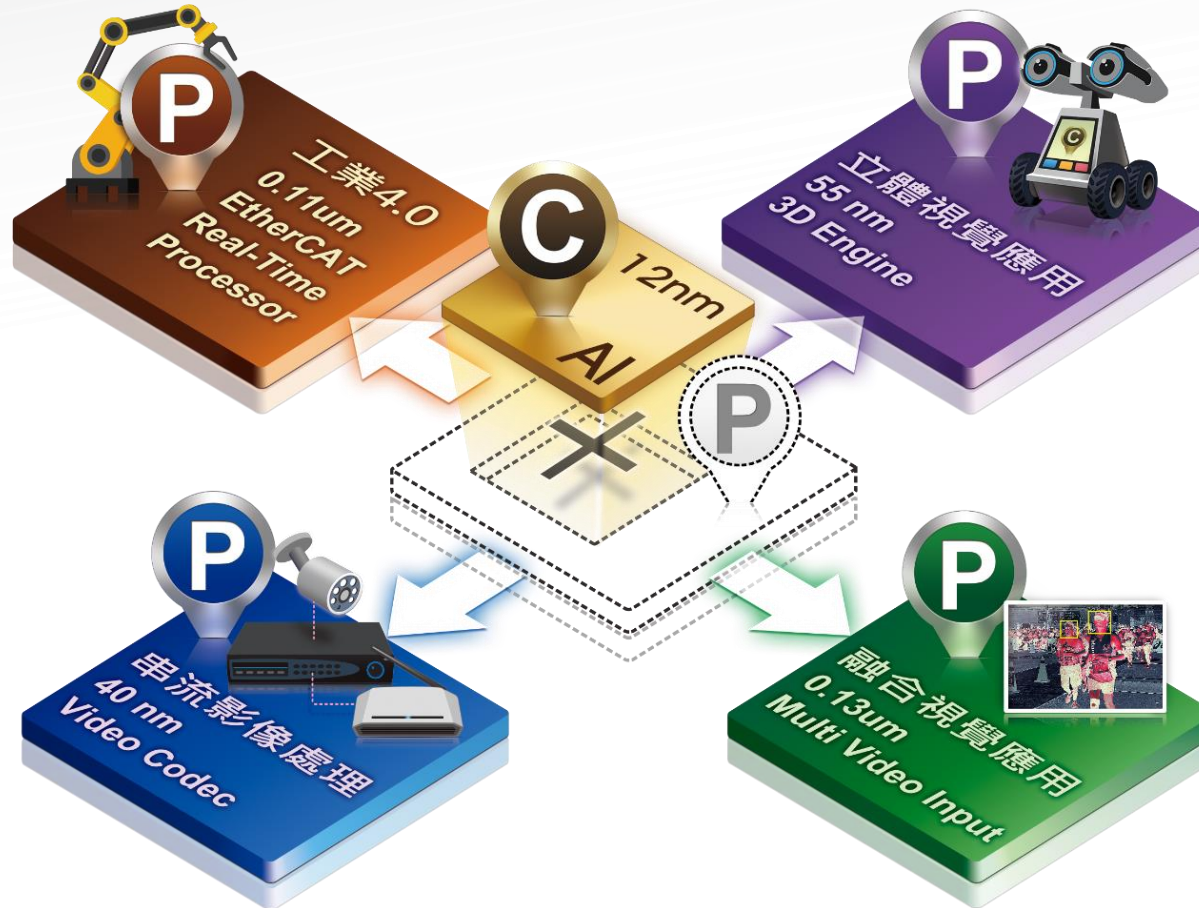


南非：
加油站付款



台灣：
醫療終端設備

+ AI on Chip EVERY



C3V Application : Robot Market

Smart Robot everywhere in the world

■ Applications

- 掃地機_識別物件、自走避障
- 戶外割草機_識別物件、自走避障
- 長照監護系統_跌倒、落床
- 空拍機_人車救援追蹤
- 視訊會議_人臉追蹤、環境降噪
- 自走機器人_識別物件、自走避障
- 車內駕駛偵測_動作識別





SUNPLUS



Make difference